

	L #	Hits	Search Text	DBs
1	L1	1318	430/321.ccls.	US-PGPUB; USPAT
2	L2	4443	430/5.ccls.	US-PGPUB; USPAT
3	L3	931	216/2.ccls.	US-PGPUB; USPAT
4	L4	701	216/24.ccls.	US-PGPUB; USPAT
5	L5	93896	(wafer or silicon).ti,ab.	US-PGPUB; USPAT
6	L6	76526	(aperture or diaphragm).ti,ab.	US-PGPUB; USPAT
7	L7	1232	5 and 6	US-PGPUB; USPAT
8	L8	22398	(dope or doped or doping) with boron	US-PGPUB; USPAT
9	L9	91	7 and 8	US-PGPUB; USPAT
10	L10	39	1 and 6	US-PGPUB; USPAT
11	L11	38	7 and 2	US-PGPUB; USPAT
12	L12	699	((dope or doped or doping) with boron).ti,ab.	US-PGPUB; USPAT
13	L13	11	(1 or 2 or 3 or 4) and 12	US-PGPUB; USPAT
14	L14	2	4 and 7	US-PGPUB; USPAT
15	L15	39	6 and 3	US-PGPUB; USPAT

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16	L16	41	cordes-steven\$.in.	US-PGPUB; USPAT
17	L17	11	cordes-michael\$.in.	US-PGPUB; USPAT
18	L18	46	speidell-james\$.in.	US-PGPUB; USPAT
19	L19	18	mansfield-scott\$.in.	US-PGPUB; USPAT
20	L20	26	(16 or 17 or 18 or 19) and (5 or 6 or 12)	US-PGPUB; USPAT
21	L21	1	5 and 6 and 12	US-PGPUB; USPAT
22	L22	1445559	membrane or layer	US-PGPUB; USPAT
23	L23	9172	8 with 22	US-PGPUB; USPAT
24	L24	569868	wafer or silicon	US-PGPUB; USPAT
25	L25	4212	23 with 24	US-PGPUB; USPAT
26	L26	44565	etch\$.ti,ab.	US-PGPUB; USPAT
27	L27	13193	5 and 26	US-PGPUB; USPAT
28	L29	511	25 and 27	US-PGPUB; USPAT
29	L30	33073	(dope or doped or doping or boron).ti,ab.	US-PGPUB; USPAT
30	L31	212	29 and 30	US-PGPUB; USPAT

	L #	Hits	Search Text	DBs
31	L32	2293609	membrane or layer	EPO; JPO; DERWE NT; IBM_TDB
32	L33	588535	wafer or silicon	EPO; JPO; DERWE NT; IBM_TDB
33	L34	3309	(dope or doped or doping) with boron	EPO; JPO; DERWE NT; IBM_TDB
34	L35	689	32 with 33 with 34	EPO; JPO; DERWE NT; IBM_TDB
35	L36	259933	etch\$4	EPO; JPO; DERWE NT; IBM_TDB
36	L37	197	35 and 36	EPO; JPO; DERWE NT; IBM_TDB